Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	571	279/3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:49
L2	1599	118/730	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:51
L3	2738	118/500	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:51
L4	0	"134"/\$.ccls. and porous with chuck near table	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:52
L5	0	"134"/\$.ccls. and porous with chuck with table	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:52
L6	1	"134"/\$.ccls. and porous with plate and chuck with table	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:52
L7	11	"134"/\$.ccls. and porous with plate and chuck with vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:53
L8	41	"134"/\$.ccls. and porous and chuck with vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:53

L9	118	"156"/\$.ccls. and porous and chuck with vacuum	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:57
L10	154	porous and chuck with vacuum and time with forc\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:58
S1	1065	257/797	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:28
S2	2657	257/786	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/04 20:06
S3	3372	257/737	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/04 20:22
S4	2817	257/738	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/04 20:23
S5	186342	(semiconductor or die or chip or IC) and align\$4	USPAT	OR	ON	2005/02/09 13:44
S6	34149	(semiconductor or die or chip or IC) and align\$4 with (pad or post or contact or terminal)	USPAT	OR	ON	2005/02/09 13:45
S7	8637	(semiconductor or die or chip or IC) and align\$4 with (pad)	USPAT	OR	ON	2005/02/12 00:30
S8	4509	S7 and solder\$4	USPAT	OR	ON	2005/02/09 13:46
S9	2586	S8 and "257"/\$.ccls.	USPAT	OR	ON	2005/02/09 13:47
S10	1926	S9 and (redistribution or interconnect\$3 or interposer)	USPAT	OR	ON	2005/02/09 19:55
S11	95391	"9" not "10"	USPAT	OR	ON	2005/02/09 19:54
S12	5630	"s9" not "s10"	USPAT	OR	ON	2005/02/09 19:54
S13	8637	(semiconductor or die or chip or IC) and align\$4 with (pad)	USPAT	OR	ON	2005/02/09 19:54

S14	4509	S13 and solder\$4	USPAT	OR	ON	2005/02/09 19:54
S15	2586	S14 and "257"/\$.ccls.	USPAT	OR	ON	2005/02/09 19:54
S16	1926	S15 and (redistribution or interconnect\$3 or interposer)	USPAT	OR	ON	2005/02/09 19:55
S17	660	S15 not S16	USPAT	OR	ON	2005/02/09 19:56
S18	1923	S14 not S15	USPAT	OR	ON	2005/02/09 19:56
S19	1	"4926452".PN.	USPAT; USOCR	OR	OFF	2005/02/11 21:59
S20	1	"5465152".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:00
S21	1	"6272204".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:11
S22	1	"6404206".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:11
S23	1	"4811082".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:12
S24	1	"4814857".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:12
S25	1	"5338970".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:12
S26	1	"6290334".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:12
S27	1	"6356166".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:13
S28	1	"3811186".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:13
S29	1	"5056215".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:13
S30	1	"5173220".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:13
S31	1	"5264061".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:14
S32	1	"5278442".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:14
S33	1	"5484314".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:14
S34	1	"5633535".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:14
S35	1	"5705117".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:14
S36	1	"5841198".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:14

S37	1	"6140707".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:15
S38	1	"6165885".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:15
S39	1	"6255143".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:15
S40	. 1	"6281577".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:15
S41	1	"6313522".PN.	USPAT; USOCR	OR	OFF.	2005/02/11 22:15
S42	1	"6316286".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:15
S43	1	"6358776".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:16
S44	1	"6399421".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:16
S45	1	"6420213".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:16
S46	1	"6440774".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:16
S 4 7	1	"6444489".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:17
S48	1	"6461881".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:17
S49	1	" 44 78352".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:18
S50	1	"4973948".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:18
S51	1	"4977993".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:18
S52	1	"5279975".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:18
S53	1	"5375320".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:18
S54	1	"5483741".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:19
S55	1	"5496777".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:19
S56	1	"5641113".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:19
S57	1	"5668061".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:19
S58	1	"5674785".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:19

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S59	1	"5703303".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:20
S60	1	"5703402".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:20
S61	1	"5716889".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:20
S62	1	"5729894".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:20
S63	1	"5777392".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:21
S64	1	"5831445".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:21
S65	1	"5859707".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:21
S66	1	"5872051".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:21
S67	1	"5880590".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:21
S68	1	"5904555".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:22
S69	1	"5923995".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:22
S70	1	"5942805".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:22
S71	1	"5961722".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:22
S72	1	"6001703".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:22
S73	1	"6006739".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:22
S74	1	"6011694".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:22
S75	1	"6012502".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:23
S76	1	"6013535".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:23
S77	1	"6018249".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:23
S78	1	"6020218".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:23
S79	1	"6025212".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:25
S80	1	"6040702".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:25

S81	1	"6043670".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:25
S82	1	"6047470".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:26
S83	1	"6048744".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:26
S84	1	"6048755".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:26
S85	1	"6048755".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:26
S86	1	"6049974".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:26
S87	1	"6049977".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:26
S88	1	"6054338".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:27
S89	1	"6072236".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:27
S90	1	"6072700".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:27
S91	1	"6078506".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:27
S92	1	"6081040".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:28
S93	1	"6083820".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:28
S94	1	"6084311".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:28
S95	1	"6096165".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:28
S96	1	"6101148".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:28
S97	1	"6158647".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:28
S98	1	"6239380".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:28
S99	1	"6242271".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:29
S10 0	1	"6245646".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:29
S10 1	1	"6267167".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:29
S10 2	1	"62810 44 ".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:29

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S10 3	1	"6303470".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:29
S10 4	1	"6311890".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:32
S10 5	1	"6321739".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:32
S10 6	1	"6329832".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:32
S10 7	1	"6336973".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:32
S10 8	1	"6346152".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:32
S10 9	1	"6368897".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:33
S11 0	1	"6369602".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:33
S11 1	1	"6397715".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:33
S11 2	1	"6439450".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:33
S11 3	1	"6440777".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:33
S11 4	1	"6472901".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:34
S11 5	1	"6485778".PN.	USPAT; USOCR	OR.	OFF	2005/02/11 22:34
S11 6	1	"6521287".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:34
S11 7	1	"6521287".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:34
S11 8	1	"6537400".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:34
S11 9	1	"6544803".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:34
S12 0	1	"6545498".PN.	USPAT; USOCR	OR	OFF	2005/02/11 22:35
S12 1	1113	257/797	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/11 23:01

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S12 2	2814	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/11 23:07
S12 3	3602	257/737	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/11 23:32
S12 4	3043	257/738	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/11 23:32
S12 5	1	"11065160"	JPO	OR	OFF	2005/02/12 00:12
S12 6	10	(semiconductor or die or chip or IC) and align\$4 with (pad) near (index or mark or code)	USPAT	OR	ON	2005/02/12 00:35
S12 7	29	(semiconductor or die or chip or IC) and align\$4 with (pad) and pad near (index or mark or code)	USPAT	OR	ON	2005/02/14 11:23
S12 8	29	(semiconductor or die or chip or IC) and align\$4 with (pad) and pad near (index or mark or code)	USPAT	OR	ON	2005/02/14 11:24
S12 9	86	(semiconductor or die or chip or IC) and align\$4 with (pad) and pad near (index or mark or code or reference)	USPAT	OR	ON	2005/02/14 14:58
S13 0	852	257/797	USPAT	OR	ON	2005/02/14 11:26
S13 1	1	"5744379".PN.	USPAT; USOCR	OR	OFF	2005/02/14 12:06
S13 2	1	"5834323".PN.	USPAT; USOCR	OR	OFF	2005/02/14 12:07
S13 3	1	"5970310".PN.	USPAT; USOCR	OR	OFF	2005/02/14 12:07
S13 4	1	"6048750".PN.	USPAT; USOCR	OR .	OFF	2005/02/14 12:08
S13 5	1	"6069567".PN.	USPAT; USOCR	OR	OFF	2005/02/14 12:09
S13 6	1	"6121069".PN.	USPAT; USOCR	OR	OFF	2005/02/14 12:09

S13	1	"6278193".PN.	USPAT;	OR	OFF	2005/02/14 12:09
7	ī	02/0133 .FIV.	USOCR	OK	OH	2003/02/14 12.09
S13 8	66	(semiconductor or die or chip or IC) and (alignment or aligning) with (pad) and pad near (index or mark or code or reference)	USPAT	OR	ON	2005/02/14 14:59
S13 9	35	"5381307"	USPAT	OR	OFF	2005/02/14 16:27
S14 0	1221	interposer and pad	USPAT	OR	OFF	2005/02/14 16:28
S14 1	1093	S140 and (semiconductor or die or chip or IC)	USPAT	OR	OFF	2005/02/14 17:02
S14 2	8112	(semiconductor or die or chip or IC) and (PCB or board or carrier) with pad	USPAT	OR	OFF	2005/02/14 17:03
S14 3	16	S142 and pad with under near layer	USPAT	OR	OFF	2005/02/14 17:04
S14 4	26	S142 and pad with thought	USPAT	OR	OFF	2005/02/14 17:05
S14 5	209	S142 and pad with though	USPAT	OR	OFF	2005/02/14 17:05
S14 6	967	257/797	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 13:16
S14 7	2318	257/786	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 13:31
S14 8	3383	257/737	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 13:48
S14 9	3066	257/738	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 14:05
S15 0	3224	438/14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 14:22

S15 1	1466	438/15	US-PGPUB; USPAT; USOCR;	OR	OFF	2005/05/13 14:40
			EPO; JPO; DERWENT; IBM_TDB			
S15 2	1400	438/16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 14:53
S15 3	1657	438/17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 15:06
S15 4	1218	438/18	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 15:21
S15 5	798	438/401	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 15:37
S15 6	998	438/460	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 15:44
S15 7	158	438/461	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 15:53
S15 8	992	438/462	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 15:55

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S15 9	198	438/463	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:02
S16 0	698	438/464	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:06
S16 1	308	438/465	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:12
S16 2	1972	438/613	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:14
S16 3	1068	438/614	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:28
S16 4	396	438/615	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:36
S16 5	275	438/616	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:39
S16 6	650	438/617	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:42

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S16 7	15	257/E23.179	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:42
S16 8	319	228/180	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:47
S16 9	75	228/22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/13 16:47
S17 0	7	"6525413"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/09 18:31
S17 1	8	451/289 and porous with plate same vacuum with chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:24
S17 2	1	porous with plate same vacuum with chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:24
S17 3	4	porous with plate same chuck near table and chuck near table with vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:37
S17 4	8	porous with plate and chuck near table and chuck near table with vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:37
S17 5	15	porous with plate same chuck near table and chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:37

S17 6	1	(holes or open\$3 or passages) with porous with plate same chuck near table and chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:39
S17 7	3	(holes or open\$3 or passages) same porous with plate same chuck near table and chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:40
S17 8	1	(holes or open\$3 or passages) with porous with plate and porous with plate same chuck near table and chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:40
S17 9	1	(holes or open\$3 or passages) with porous with plate and plate same chuck near table and chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:40
S18 0	1	(holes or open\$3 or passages) with porous with plate and plate same chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:41
S18 1	3	(holes or open\$3 or passages) with plate and porous with plate same chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 17:57
S18 2	5	(holes or open\$3 or passages) same plate and porous with plate same chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:01
S18 3	1	(holes or open\$3 or passages) same plate and porous with plate same chuck near table and chuck near table with (grooves or recesses or apertures or cavity)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:06
S18 4	0	vacuum near line same plate and porous with plate same chuck near table and chuck near table with (grooves or recesses or holes or open\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:08
S18 5	0	vacuum near line same plate and porous with plate same chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:08

S18 6	0	vacuum near line same plate and porous with plate same chuck near table and chuck near table with (grooves or recesses or holes or open\$3 or channels)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:08
S18 7	0	vacuum near lines same (plate or layer or film) and porous with (plate or layer or film) same chuck near table and chuck near table with (grooves or recesses or holes or open\$3 or channels)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:09
S18 8	2	vacuum same (plate or layer or film) and porous with (plate or layer or film) same chuck near table and chuck near table with (grooves or recesses or holes or open\$3 or channels)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:12
S18 9	3	(vacuum or suction) same (plate or layer or film) and porous with (plate or layer or film) same chuck near table and chuck near table with (grooves or recesses or holes or open\$3 or channels)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:13
S19 0	0	(vacuum or suction) with lines and porous with (plate or layer or film) same chuck near table and chuck near table with (grooves or recesses or holes or open\$3 or channels)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:13
S19 1	5	(vacuum or suction) and porous with (plate or layer or film) same chuck near table and chuck near table with (grooves or recesses or holes or open\$3 or channels)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/13 18:15
S19 2	26	(vacuum or suction) and porous same chuck near table and chuck near table with (grooves or recesses or holes or open\$3 or channels)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:06
S19 3	70	(vacuum or suction) and porous same chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 13:57
S19 4	86	porous same chuck near table	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 17:45

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S19 5	16	S194 not S193	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 14:49
S19 6	877	451/289	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 14:49
S19 7	877	451/289	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 17:14
S19 8	575	451/388	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 18:27
S19 9	964	porous same chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 19:49
S20 0	633	porous with chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 17:45
S20 1	229	porous with chuck and (holes or open\$3 or via or channels or passages or grooves) with porous	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 17:46
S20 2	448	257/3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 19:08
S20 3	2645	118/500	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 19:02

S20	1544	118/730	US-PGPUB;	OR	ON	2005/06/14 19:03
4			USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB			
S20 5	549	279/3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 19:08
S20 6	19	("134"/\$.ccls.) and porous same chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 19:51
S20 7	65	("156"/\$.ccls.) and porous same chuck	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/14 19:52
S20 8	915	451/289	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 15:55
S20 9	604	451/388	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 16:07
S21 0	565	279/3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/11/21 16:08
S21 1	1076	257/797	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:32

S21 2	2622	257/786	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:34
S21 3	3872	257/737	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:36
S21 4	3519	257/738	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:40
S21 5	19	257/E23.179	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:46
S21 6	3657	438/14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:52
S21 7	1606	438/15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:55
S21 8	1569	438/16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 12:59
S21 9	1873	438/17	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:11

S22 0	1369	438/18	US-PGPUB; USPAT; USOCR; EPO; JPO;	OR	OFF	2006/03/06 13:18
			DERWENT; IBM_TDB			
S22 1	912	438/401	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:21
S22 2	1195	438/460	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:33
S22 3	2	"6329703".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:32
S22 4	2	"5895970".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:32
S22 5	180	438/461	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:34
S22 6	1129	438/462	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:36
S22 7	240	438/463	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:39

S22 8	842	438/464	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:43
S22 9	351	438/465	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:47
S23 0	2323	438/613	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:48
S23 1	1229	438/614	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:49
S23 2	455	438/615	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:50
S23 3	305	438/616	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 13:57
S23 4	751	438/617	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:00
S23 5	327	228/180	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:03

S23 6	79	228/22	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:05
S23 7	936	451/289	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:10
S23 8	624	451/388	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/06 14:48